iC-LFMB

64x1 LINEAR IMAGE SENSOR

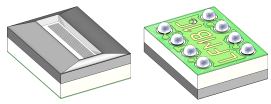
FEATURES

- 64 active photo pixels of 56 µm x 600 µm
- 63.5 µm pitch (400 DPI)
- Integrating L-V conversion followed by a sample & hold circuit
- High sensitivity and uniformity over wavelength
- High pixel clock rate of up to 5 MHz
- Only 64 clocks required for readout
- Shutter function enables flexible integration times
- Glitch-free analogue output
- Push-pull output amplifier
- 5 V single supply operation

APPLICATIONS

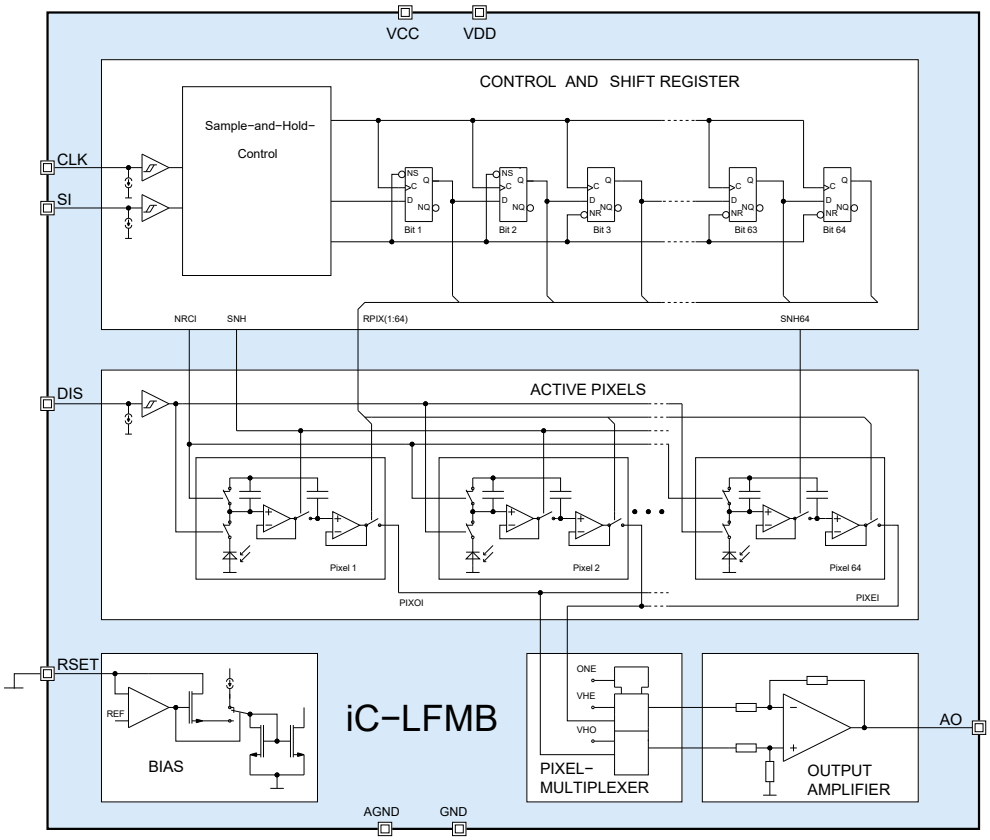
- Optical line sensors
- CCD substitute

PACKAGES



oBGA LFMB1C

BLOCK DIAGRAM



DESCRIPTION

iC-LFMB is an integrating light-to-voltage converter with a single line of 64 pixels pitched at 63.5 µm (center-to-center distance). Each pixel consists of a 56.4 µm x 600 µm photodiode, an integration capacitor and a sample and hold circuit.

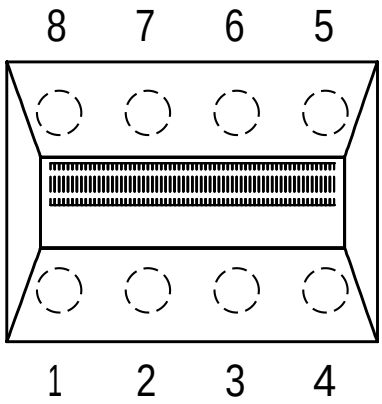
The integrated control logic makes operation very simple, with only a start and clock signal necessary. A third control input enables the integration period to be paused at any time (electronic shutter).

With the start signal the hold mode is activated for all pixels simultaneously with the next rising clock edge; starting with pixel 1 the hold voltages are switched in sequence to the push-pull output amplifier. The second clock pulse discharges all integration capacitors and the integration period starts again in the background during the output phase. A run is complete after 64 clock pulses.

iC-LFMB supports high clock rates up to 5 MHz.

PACKAGING INFORMATION

PIN CONFIGURATION oBGA LFMB1C



PIN FUNCTIONS

No.	Name	Function
1	SI	Start Integration Input
2	CLK	Clock Input
3	AO	Analogue Output
4	VCC	+5 V Supply Voltage
5	RSET	Connect to GND for internal bias
6	AGND	Analogue Ground
7	GND	Digital Ground
8	DIS	Global Shutter

ABSOLUTE MAXIMUM RATINGS

Beyond these values damage may occur; device operation is not guaranteed.

Item No.	Symbol	Parameter	Conditions	Min.	Max.	Unit
G001	VDD	Digital Supply Voltage		-0.3	6	V
G002	VCC	Analogue Supply Voltage		-0.3	6	V
G003	V()	Voltage at SI, CLK, DIS, RSET, AO		-0.3	VCC + 0.3	V
G004	I()	Current in RSET, AO		-10	10	mA
G005	Vd()	ESD Susceptibility at all pins	HBM, 100 pF/1.5 kΩ		4	kV
G006	Tj	Junction Temperature		-40	150	°C
G007	Ts	Chip Storage Temperature		-40	150	°C

THERMAL DATA

Operating Conditions: VCC = VDD = 5 V ±10%

Item No.	Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
T01	Ta	Operating Ambient Temperature Range	see package specification				

All voltages are referenced to ground unless otherwise stated.
All currents flowing into the device pins are positive; all currents flowing out of the device pins are negative.

ELECTRICAL CHARACTERISTICS

Operating Conditions: VCC = VDD = 5 V ±10%, RSET = GND, Tj = -25...85 °C unless otherwise noted

Item No.	Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Total Device							
001	VDD	Digital Supply Voltage Range		4.5		5.5	V
002	VCC	Analogue Supply Voltage Range		4.5		5.5	V
003	I(VDD)	Supply Current in VDD	f(CLK) = 1 MHz			0.25	mA
004	I(VCC)	Supply Current in VCC		2		7	mA
005	Vc()hi	Clamp Voltage hi at SI, CLK, DIS, RSET	Vc()hi = V() − VCC; I() = 1 mA	0.3		1.8	V
006	Vc()lo	Clamp Voltage lo at SI, CLK, DIS, RSET	Vc()hi = V() − V(AGND); I() = -1 mA	-1.5		0.3	V
007	Vc()hi	Clamp Voltage hi at AO	Vc()hi = V(AO) − VCC; I(AO) = 1 mA	0.3		1.5	V
008	Vc()lo	Clamp Voltage lo at AO, VCC, VDD, GND	Vc()lo = V() − V(AGND); I() = -1 mA	-1.5		-0.3	V
Photodiode Array							
201	A()	Radiant Sensitive Area	600 µm x 56.40 µm per Pixel		0.03384		mm^2
202	S(λ)max	Spectral Sensitivity	λ = 680 nm (see Fig. 1)		0.5		A/W
203	λ_{ar}	Spectral Application Range	S(λ_{ar}) = 0.25 x S(λ)max (see Fig. 1)	400		980	nm
Analogue Output AO							
301	Vs()lo	Saturation Voltage lo	I() = 1 mA			0.5	V
302	Vs()hi	Saturation Voltage hi	Vs()hi = VCC − V(), I() = -1 mA			1	V
303	K	Sensitivity	λ = 680 nm		2.88		V/pWs
304	V0()	Offset Voltage	integration time 1 ms, no illumination		400	800	mV
305	ΔV0()	Offset Voltage Deviation during integration mode	ΔV0() = V(AO)t1 − V(AO)t2, Δt = t2 − t1 = 1 ms	-250		50	mV
306	ΔV()	Signal Deviation during hold mode	ΔV0() = V(AO)t1 − V(AO)t2, Δt = t2 − t1 = 1 ms	-150		150	mV
307	tp(CLK-AO)	Settling Time	Cl(AO) = 10 pF, CLK lo → hi until V(AO) = 0.98 x V(VCC)			200	ns
Power-On-Reset							
801	VCCon	Power-On Release by VCC				4.4	V
802	VCCoff	Power-Down Reset by VCC		1			V
803	VCChys	Hysteresis	VCChys = VCCon − VCCoff	0.4	1	2	V
Input Interface SI, CLK, DIS							
B01	Vt()hi	Threshold Voltage hi				2	V
B02	Vt()lo	Threshold Voltage lo		0.8			V
B03	Vt()hys	Hysteresis	Vt()hys = Vt()hi − Vt()lo	100		250	mV
B04	I()	Pull-Down Current		10	30	50	µA
B05	fclk	Permissible Clock Frequency				5	MHz

OPTICAL CHARACTERISTICS: Diagrams

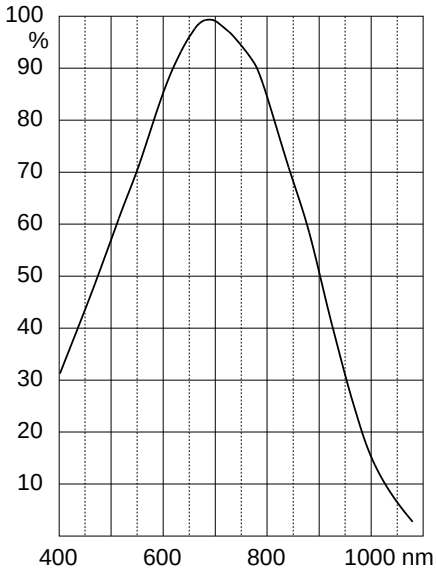


Figure 1: Relative spectral sensitivity

OPERATING REQUIREMENTS: Logic

Operating Conditions: VCC = VDD = 5 V ±10%, Tj = -25...85 °C
input levels lo = 0...0.45 V, hi = 2.4 V...VCC, see Fig. 2 for reference levels

Item No.	Symbol	Parameter	Conditions	Min.	Max.	Unit
l001	tset	Setup Time: SI stable before CLK lo → hi	see Fig. 3	50		ns
l002	thold	Hold Time: SI stable after CLK lo → hi	see Fig. 3	50		ns

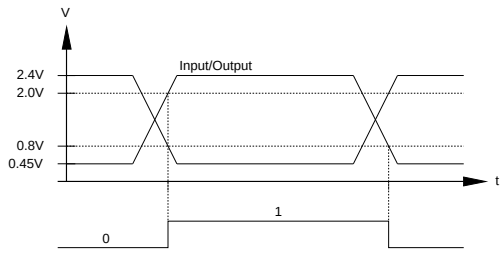


Figure 2: Reference levels

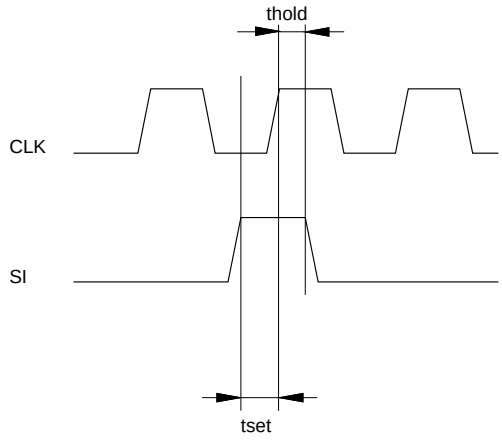


Figure 3: Timing diagram

DESCRIPTION OF FUNCTIONS

Normal operation
Following an internal power-on reset the integration and hold capacitors are discharged and the sample and hold circuit is set to sample mode. A high signal at SI and a rising edge at CLK triggers a readout cycle and with it a new integration cycle.

In this process the hold capacitors of pixels 1 to 63 are switched to hold mode immediately (SNH = 1), with pixel 64 (SNH64 = 1) following suit one clock pulse later. This special procedure allows all pixels to be read out with just 64 clock pulses. The integration capacitors are discharged by a one clock long reset signal (NRCI = 0) which occurs between the 2nd and 3rd falling edge of the readout clock pulse (cf. Figure 4). After the 63 pixels have been read out these are again set to sample mode (SNH = 0), likewise for pixel 64 one clock pulse later (SNH64 = 0).

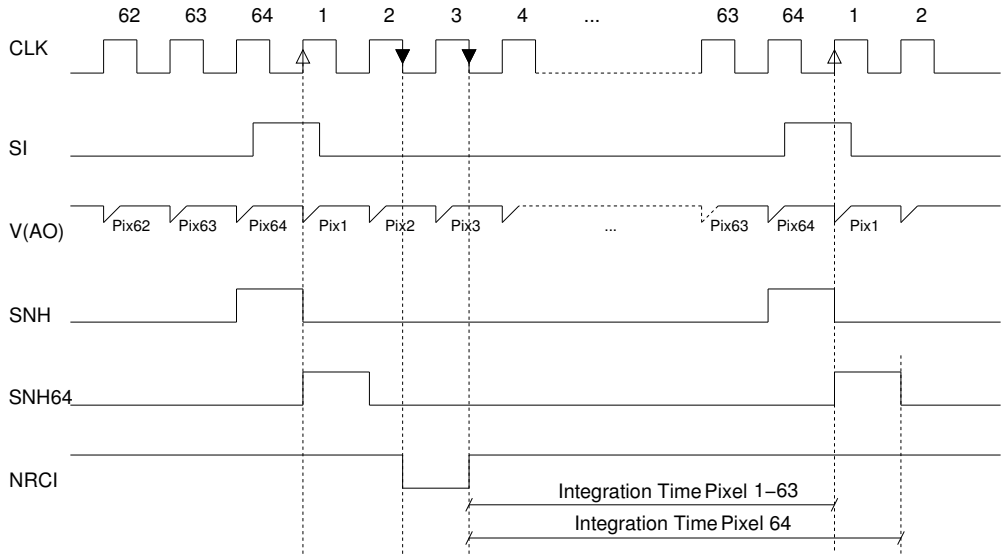


Figure 4: Readout cycle and integration sequence

If prior to the 64th clock pulse a high signal occurs at SI the present readout is halted and immediately re-initiated with pixel 1. In this instance the hold capacitors retain their old value i.e. hold mode prevails (SNH/SNH64 = 0).

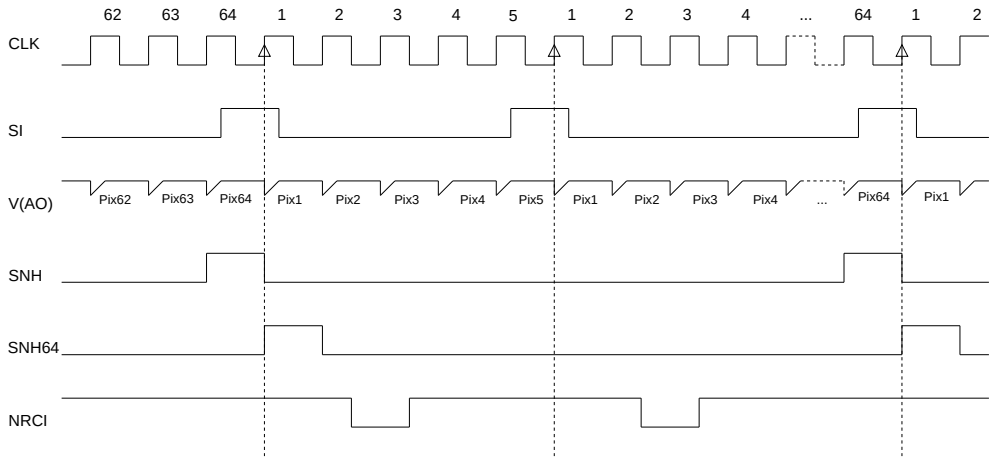


Figure 5: Restarting a readout cycle

With more than 64 clock pulses until the next SI signal, pixel 1 is output without entering hold mode; the output voltage tracks the voltage of the pixel 1 integration capacitor.

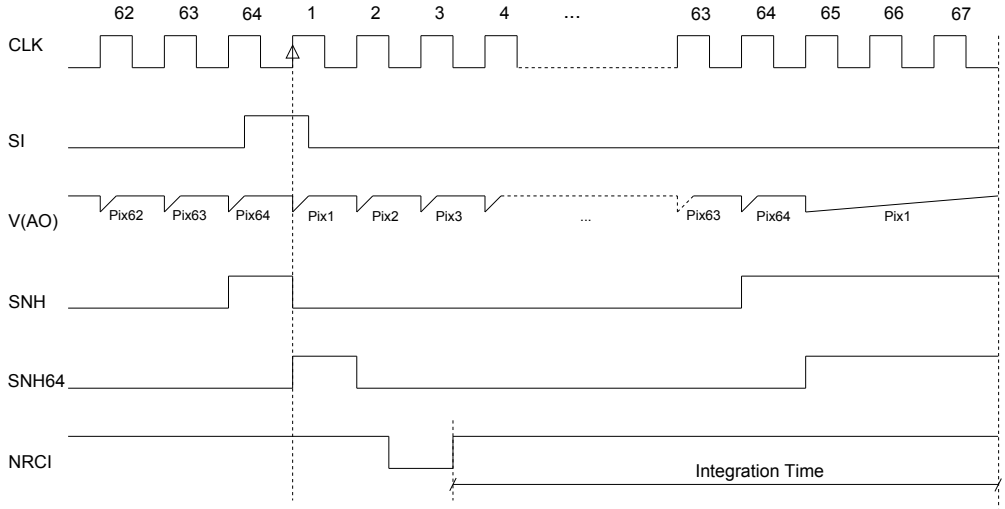


Figure 6: Clock pulse continued without giving a new integration start signal

Operation with the shutter function
Integration can be halted at any time via pin DIS, i.e. the photodiodes are disconnected from their corresponding integration capacitor when DIS is high and the current integration capacitor voltages are maintained. If this pin is open or switched to GND the pixel photocurrents are summed up by the integration capacitors until the next successive SI signal follows.

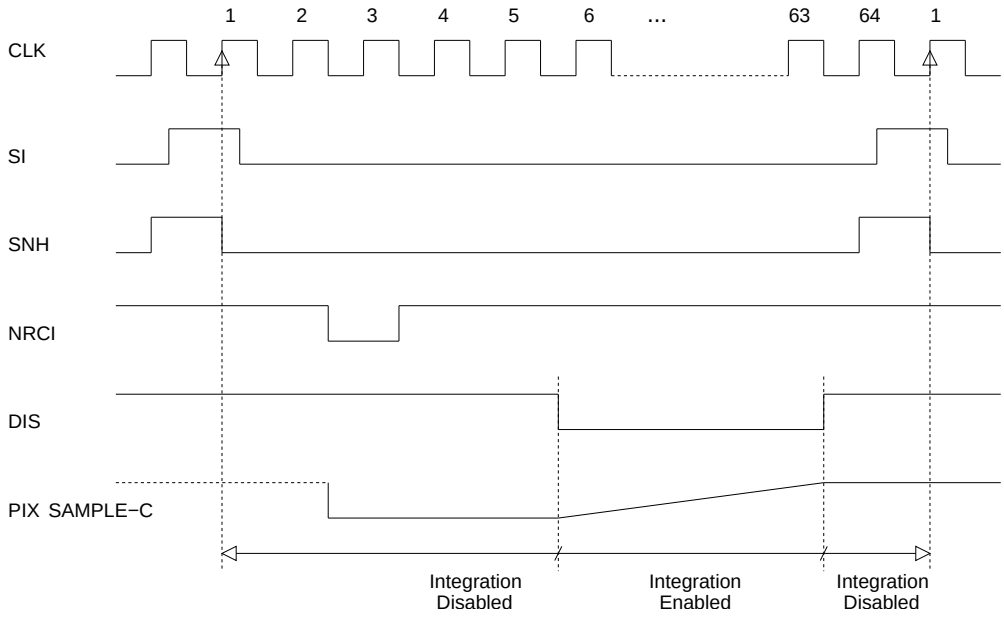


Figure 7: Defining the integration time via shutter input DIS

ORDERING INFORMATION

Type	Package	Order Designation
iC-LFMB	oBGA™ LFMB1C	iC-LFMB oBGA LFMB1C

Please send your purchase orders to our order handling team:

Fax: +49 (0) 61 35 - 92 92 - 692
E-Mail: dispo@ichaus.com

For technical support, information about prices and terms of delivery please contact:

iC-Haus GmbH
Am Kuemmerling 18
D-55294 Bodenheim
GERMANY

Tel.: +49 (0) 61 35 - 92 92 - 0
Fax: +49 (0) 61 35 - 92 92 - 192
Web: https://www.ichaus.com
E-Mail: sales@ichaus.com

Appointed local distributors: https://www.ichaus.com/sales_partners